Past Accomplishments and New Project Opportunities

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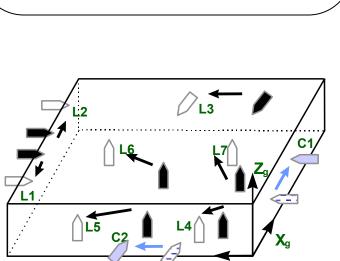
Fixturing: Modeling & Analysis

(Sponsors: Ford, GM, NSF, Caterpillar)

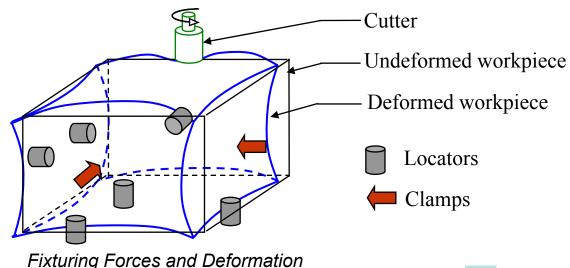
Objectives:

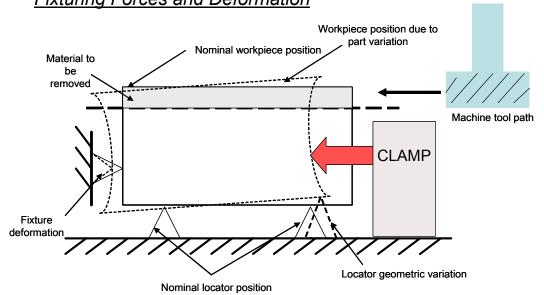
Develop and verify models for:

- prediction of fixture-workpiece contact forces/deformations
- synthesis of fixture layout and clamping forces
- prediction of part location errors



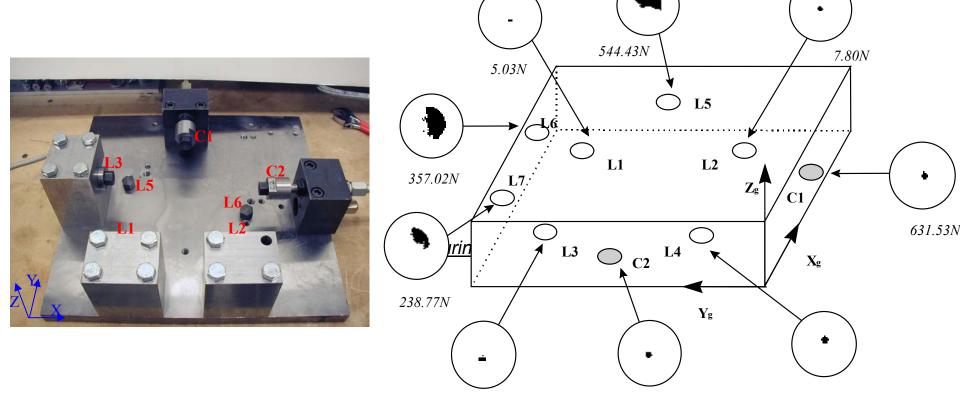
Fixture Layout/Clamping
Force Synthesis





Part Location Error Sources

Modeling & Analysis Results



Major Deliverables (Ford, GM, Caterpillar):

• Matlab® codes for analysis of fixture-workpiece contact forces/deformations and optimization of clamping force

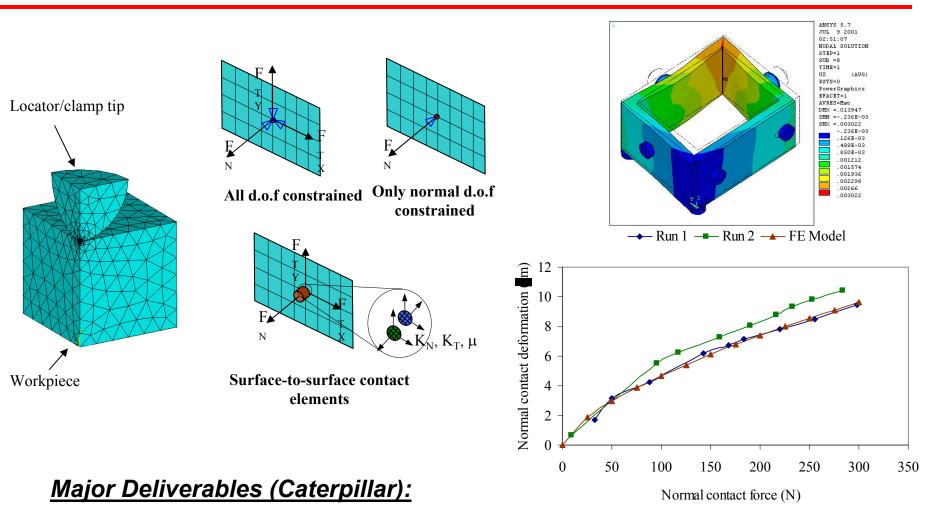
7.71N

11.92N

631.53N

Code implemented by sponsor (Ford AMTD, Livonia Plant)

Modeling & Analysis Results



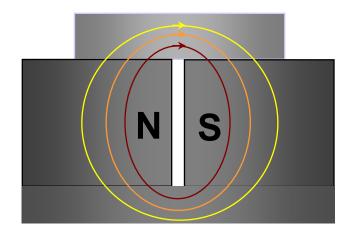
- "Best practice" rules for fixture-workpiece contact modeling using the FEM.
- ABAQUS® modules for spherical/planar contact fixture-workpiece contact modeling

Flexible Fixturing

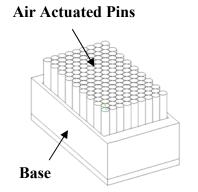
(Sponsors: Timken, Lamb Technicon, NIST/ATP)

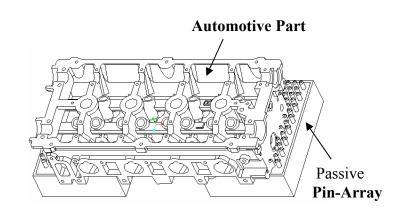
Objectives:

- Analysis of holding forces in electromagnetic chucks
- Design and analysis of pin-array flexible fixture for machining
- Develop tolerance-based fixture stiffness optimization method



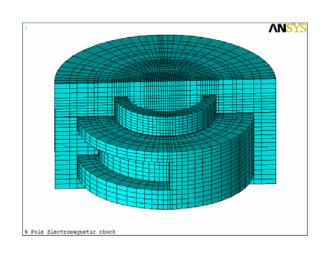
Magnetic Chuck

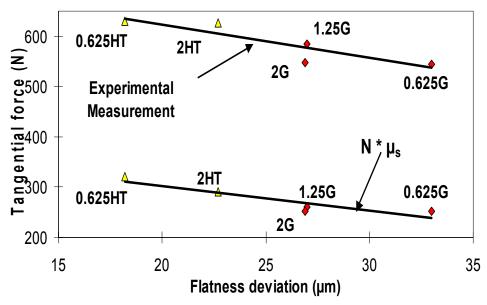




Pin-Array Flexible Fixtures

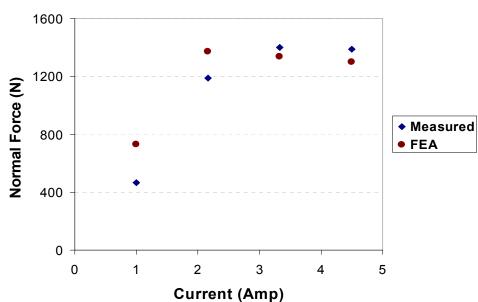
Flexible Fixturing Results



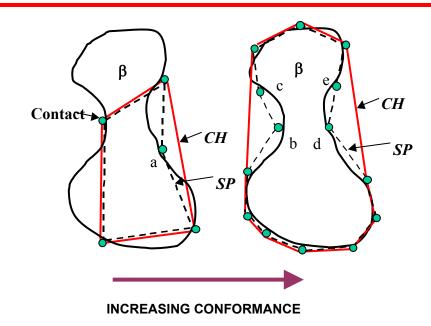


Major Deliverables (Timken):

- Holding force measurements on emag chuck
- Matlab code for estimation of normal holding force in chuck

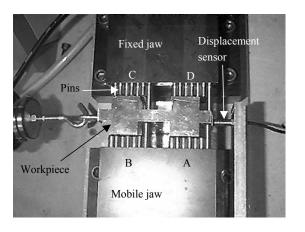


Flexible Fixturing Results

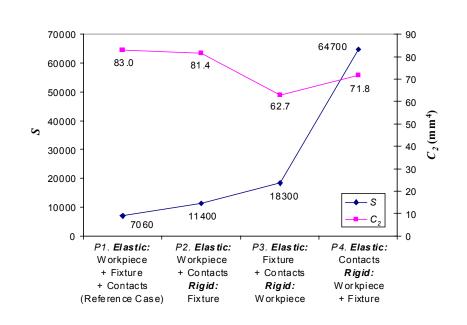




- Matlab code for optimizing pin geometry and stiffness
- Elements of pin-array fixture design
- U.S. and World-wide patents pending

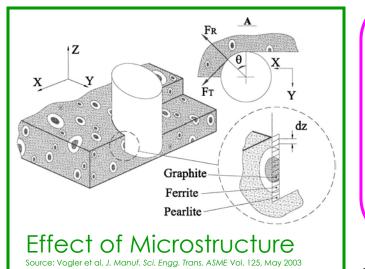


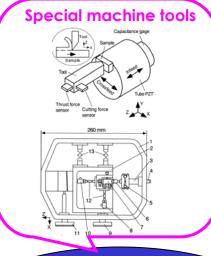
Active Pin-Array Vise Holding a Complex Part

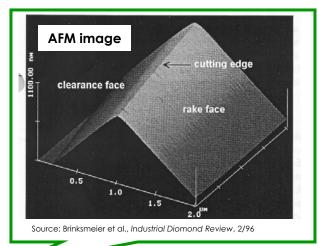


New Research Projects:

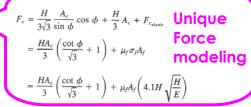
- Micro/Nano-Cutting Process Science
 - Interrupted Hard Turning
- Analysis of White Layers in Hard Turning







Effect of edge geometry

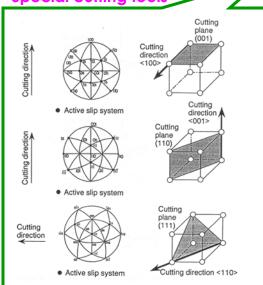




A tool edge contour of 0.05 μm (50nm/0.000002") is achieved over a wide working angle of 90°.



Special cutting tools



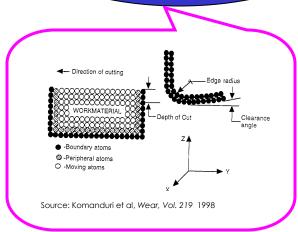
Effect of Crystal Planes

Source: Liang et al, Prec. Engg. Vol. 16, No. 2, April 1994

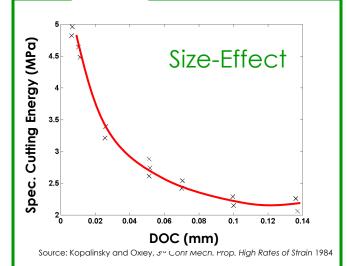
Macro Cutting

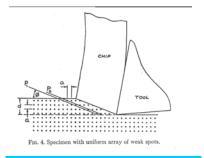
TOOLS? VS PROCESS?

Micro/Nano Cutting



MD Simulations





Shaw: Inhomogeneity

Past

Strain gradient effect

Future

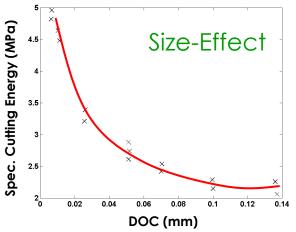
Approach:

- $F = F_{inc} + F_{dec} + F_{const}$
- Perform orthogonal cuts and observe forces
- Relate force components to atomic bond energies, fracture strain energy, etc.

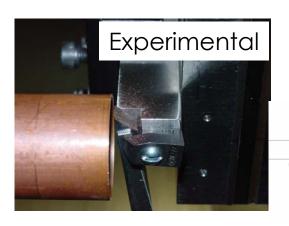
Can help understand forces and impact on surface and sub-surface

Determines how much energy is needed to cut

Why study size-effect?



Source: Kopalinsky and Oxiey, 314 Cont Mecn. Prop. High Rates of Strain 1984



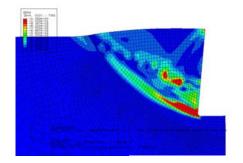
Oxley: Strain-rate effect

Approach:
Incorporate length
scale into macro
cutting models

Edge radius Effect

Past

Future



FEA modeling with Strain gradient

Interrupted Hard Turning

Goal:

 To analyze hard turning process for parts with interruptions

Motivation:

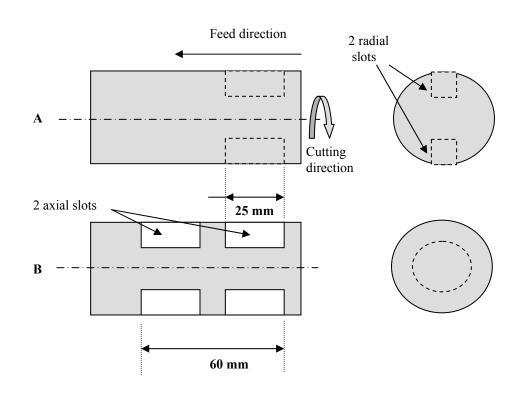
- Lack of scientific data on interrupted hard turning process
- Interruptions may be deterministic (part geom. variations) or stochastic (material inhomogeneities)

Approach:

- Experimental: forces, tool wear, surface texture/integrity
- Evaluate high-purity (binderless) cBN tools

Expected Results:

- Process data for interrupted hard turning
- Bounds on forces, tool wear, surface finish due to interruptions



Analysis of White Layers in Hard Machining

Goals:

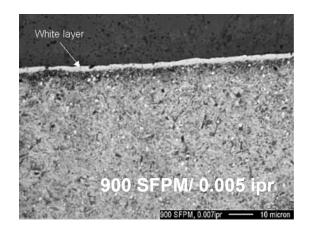
- To experimentally identify white layer formation mechanisms in hard machining
- To explain white layer formation in machining quantitatively in terms of the underlying mechanisms

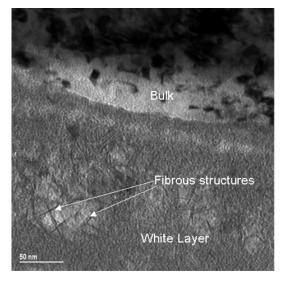
Motivation:

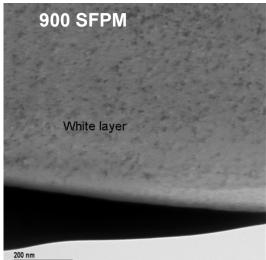
 Lack of complete understanding of white layer formation mechanisms (mechanical vs. thermal effects)

Approach:

- Using recently developed SEM techniques
- Numerical modeling







Bright-Field TEM Images